

FUNDAMENTAL ABLATION OF ARGON-FLOURIDE EXCIMER LASER ON
POLYMETHYL METHACRYLATE BY INTERFEROMETRY TECHNIQUE

HANANI BINTI YAHAYA @ JAAFAR

A thesis submitted in fulfilment of the
requirements for the award of the degree of
Master of Science (Physics)

Faculty of Science
Universiti Teknologi Malaysia

MEI 2006

To my beloved husband, parents, and families

ACKNOWLEDGEMENT

First of all, in humble way I wish to give all the Praise to Allah, the Almighty God for His mercy that gives me the strength, *keredhaanNya* and time to complete this work. With His blessing may this work be beneficial for the whole of humanity.

I wish to express my sincere gratitude and appreciation to my main thesis supervisor, Associate Professor Dr Noriah Bidin for encouragement, guidance, opinion, and enjoyable discussion throughout this study. I am also very thankful to my co-supervisor, Associate Professor Dr Mohamad Khairi Saidin for his support and suggestions. Without their continued support and interest, this thesis would not have been the same as presented here.

I am also indebted to the Government of Malaysia through IRPA scholarship and Universiti Teknologi Malaysia for funding my study. Without this financial support, this project would not possible.

In loving memory, *Allahyarham* En. Nyan Abu Bakar should also be recognised for his kindly help and assisting in carrying out experimental works. My sincere appreciation also extends to all my colleagues, friends, and others who have provided assistance at various occasions. Their views, concerns, tips, and encouragements are useful indeed. Unfortunately, it is not possible to list all of them in this limited space.

Last, but not least, I am very grateful to my beloved family especially my beloved husband for their prayers, continuing support, patience, valuable advices, and ideas throughout the duration of this study.

ABSTRACT

A fundamental study is carried out to fabricate or in other words to ablate an optical material by using a single pulse of ultraviolet light. In this case, argon fluoride excimer laser has been used as the ultraviolet light source while polymethyl methacrylate (PMMA) sample is used as the optical material. The laser ablation was conducted in between 1 to 20 pulses as a fundamental ablation. The ablation effects on the PMMA sample were analysed by using interferometry method. Straight line and equidistance fringes pattern is an indicator for smooth and flat surface. The effect of ablation was quantified by measuring shifted distance, intensity changes, and spacing reduction of fringes. The initial fringes shifted were notified as ablation threshold. This occurred after 9 pulses of exposures with corresponding threshold fluence of 3.18 mJ/mm^2 . The fringes pattern becomes peculiar and difficult to trace at higher exposures. This contributed the increasing in shifted distance and fluctuating in the fringes intensity. High degree of surface roughness is indicated by the large fraction number of half wavelength and speckle existence. The re-solidified of removal particles are possibly responsible to cause the refractive index of the tested region become fluctuated in the range of 1.43 to 1.49. By increasing number of laser pulses from 10 pulses to 20 pulses after ablation threshold, the ablation depth on the tested region was estimated and found that the depth varied in between 40 nm to 800 nm. The corresponding laser fluence had given were in between 3.6 mJ/mm^2 to 7.3 mJ/mm^2 . Hence the fundamental study succeeds to ablate the PMMA material by using ultraviolet light of excimer laser.

ABSTRAK

Satu kajian telah dijalankan bagi memfabrikasi atau dalam kata lain mengablasi bahan optik menggunakan satu denyut cahaya ultraungu. Dalam kes ini, laser eksimer argon-florida telah digunakan sebagai sumber cahaya ultraungu manakala sampel polimethyl methakrilat (PMMA) digunakan sebagai bahan optik. Pengablasi laser telah diuji pada asasnya menggunakan 1 hingga 20 denyutan laser. Kesan ablasi ke atas sampel PMMA telah dianalisis menggunakan kaedah interferometri. Garis lurus dan jarak pinggir interferens yang sama menunjuk suatu permukaan yang rata. Kesan ablasi telah dikuantitikan dengan mengukur perubahan jarak anjakan, keamatan dan kelebaran jalur pinggir. Anjakan pertama yang berlaku pada pinggir dikenalpasti sebagai takat ablasi. Ia berlaku pada 9 bilangan denyut laser iaitu bersamaan dengan 3.18 mJ/mm^2 takat ablasi. Ini meliputi pertambahan dalam anjakan dan perubahan pada keamatan pinggir. Darjah kekasaran permukaan yang tinggi dapat dilihat berdasarkan kepada nombor pecahan separuh panjang gelombang yang besar dan kewujudan bintik laser. Pengerasan semula zarah bahan yang terkeluar berkemungkinan menjadi punca kepada perubahan indeks biasan yang berlaku pada kawasan ujian di mana ia telah berubah di antara 1.43 hingga 1.49. Dengan meningkatkan bilangan denyut dari 10 denyut ke 20 denyut selepas takat ablasi, kedalaman ablasi pada kawasan ujian telah dianggarkan dan didapati berada di antara 40 nm ke 800 nm. Tenaga per unit kawasan yang terlibat ialah di antara 3.6 mJ/mm^2 hingga 7.3 mJ/mm^2 . Oleh itu, kajian asas berjaya mengablasi bahan PMMA dengan menggunakan cahaya ultraungu daripada laser eksimer.

TABLE OF CONTENTS

CHAPTER	TITLE	PAGE
	DECLARATION	ii
	ACKNOWLEDGEMENT	iv
	ABSTRACT	v
	TABLE OF CONTENTS	vii
	LIST OF TABLES	x
	LIST OF FIGURES	xi
	LIST OF SYMBOLS	xiv
	LIST OF APPENDICES	xv
1	INTRODUCTION	1
	1.1 Overview	1
	1.2 Laser Machining	2
	1.3 Interferometric Observation	5
	1.4 Research Objective	6
	1.5 Research Scopes	6
	1.6 Thesis Outline	7
2	THEORY	9
	2.1 Introduction	9
	2.2 Laser Ablation	9
	2.3 Optical Material	12
	2.4 Refractive Index	14
	2.5 Interference - Optical Phase	16

2.6	Summary	21
3	METHODOLOGY AND MATERIAL	22
3.1	Introduction	22
3.2	Excimer Laser System	22
	3.2.1 Internal Structure	23
	3.2.2 External Triggering	25
3.3	Energy Measurement	26
3.4	Beam Profile	28
3.5	Sample Preparation	30
3.6	Interferometer	31
	3.6.1 Magnification	34
	3.6.2 Fringes Analysis	36
3.7	Summary	37
4	CHARACTERIZATION OF EXCIMER LASER BEAM	39
4.1	Introduction	39
4.2	Energy and Peak Power	39
	4.2.1 Pumping Energy	40
	4.2.2 Number of Pulses	42
4.3	Excimer Laser Beam Profile	43
	4.3.1 Beam Profile at Various Discharged Voltage	45
	4.3.2 Beam Profile at Various Working Distance	48
4.4	Energy Per Unit Area	51
4.5	Summary	52

5	DIAGNOSE THE ABLATION EFFECT BY INTERFEROMETRY METHOD	54
5.1	Introduction	54
5.2	Reference Fringes	55
5.3	Ablation Threshold	57
5.4	Ablation Effect	59
	5.4.1 Shifted Fringes	63
	5.4.2 The Changes in Fringes Intensity	67
	5.4.3 Fringes Spacing	71
5.5	Summary	76
6	DETERMINATION OF ABLATION DEPTH	78
6.1	Introduction	78
6.2	Brewster Technique	79
6.3	Refractive Index Changes	80
6.4	Ablation Depth	85
6.6	Summary	93
7	CONCLUSIONS AND SUGGESTION	94
7.1	Conclusions	94
7.2	Problems and Suggestions	97

REFERENCES

PUBLICATIONS

APPENDIX

LIST OF TABLES

TABLE NO.	TITLE	PAGE
4.1	Single pulse energy and peak power of the beam upon discharged voltage	40
4.2	Pulse energy and peak power of the laser beam at different number of pulses	42
4.3	Area of intensity distribution upon discharged voltages	47
4.4	Area of intensity distribution upon working distance	50
4.5	Energy per unit area	51
5.1	Data of shifted distance for all tested fringes (F1 to F7)	64
5.2	Data of fringes intensity for all tested fringes (F1 to F7)	67
5.3	Data of intensity changes for all tested fringes (F1 to F7)	68
5.4	Data of fringes spacing for all tested fringes (F1 to F7)	72
5.5	The flatness for all tested fringes (F1 to F7) in term of $\lambda/2$	73
6.1	Power at different angle on the exposed material	81
6.2	Refractive index of the exposed material	84
6.3	Results of calculated depth, d for 10, 12, and 14 pulses exposures	88
6.4	Results of calculated depth, d for 16, 18, and 20 pulses exposures	89

LIST OF FIGURES

FIGURE NO.	TITLE	PAGE
2.1	Hypothetical steps in the interaction of a laser beam with a polymer surface (Srinivasan, 1993)	11
2.2	Structure of polymethyl methacrylate	12
2.3	Schematic of a UV-treatment system (Garbassi <i>et al.</i> , 1998)	13
2.4	A wave reflecting and refracting at an interfaced (Hecht & Zajac, 1989)	15
2.5	Interference produced by division wavefront (Parker, 1988) (a) Young's two-pinhole interferometer (b) Lloyd's mirror	17
2.6	Interference produced by division of amplitude (Parker, 1988)	18
2.7	Formation of fringes of equal inclination by reflection in a plane-parallel plate (Hariharan, 1985)	18
3.1	An electrical discharge exciting a gas laser (Hecht, 1992)	23
3.2	Internal energy of R-H molecule in excited and ground state (Hecht, 1992)	24
3.3	An excimer laser connected to a function generator for external triggering	25
3.4	Ophir Optronics energy meter and its display	27
3.5	Experimental set up for excimer laser beam calibration	27
3.6	CCD camera Beamstar Profiler and its software	28
3.7	Option screen for Beamstar CCD laser beam profiler	29
3.8	Option windows for beam size measurement	30

3.9	Schematic diagram of sample for ablation work	31
3.10	Schematic diagram of interferometer setup over excimer laser system	33
3.11	Option windows for ruler calibration	35
3.12	Option windows for calibration set-up	36
4.1	Pulse energy of the beam versus discharged voltage	41
4.2	Pulse energy of the laser pulse versus number of pulses	43
4.3	Beam profiles of ArF excimer laser in 3D view	44
4.4	Beam profiles of ArF excimer laser in top view (2D) (Magnification 15X)	44
4.5	Beam profiles at various discharged voltages of the ArF excimer laser (Magnification 15X)	46
4.6	The laser spot area versus discharged voltage	48
4.7	Beam spot at various working distance of the ArF excimer laser (Magnification of 15X)	49
4.8	The laser spot area versus working distance. Laser operated at discharged voltage of 12 kV with repetition rate of 20 Hz	50
4.9	Energy per unit area versus number of laser pulses	52
5.1	The image of reference interference pattern (Magnification 2.5X)	55
5.2	The 'option windows' of Matrox Inspector software	56
5.3	The fringes pattern of PMMA and its spectrum profile before ablation	57
5.4	Fringes profile at threshold energy	59
5.5	Ablation interferograms and their line profiles after exposed by (a) 10 pulses (b) 12 pulses (c) 14 pulses	61
5.6	Ablation interferograms and their line profiles after exposed by (a) 16 pulses (b) 18 pulses (c) 20 pulses	62
5.7	Graph shifted distance of fringes upon number of pulses	66

5.8	Graph intensity changes upon fringes for 12, 14, and 16 pulses exposures	69
5.9	Graph intensity changes upon fringes for 18 and 20 pulses exposures	70
5.10	Option windows for spacing measurement	72
5.11	Histogram of flatness upon fringes after exposed with 10, 12, and 14 pulses	74
5.12	Histogram of flatness upon fringes after exposed with 16, 18, and 20 pulses	75
6.1	Schematic diagram of Brewster's angle measurement	80
6.2	Power of the laser beam versus incidence angle for 10, 12, and 14 pulses exposures	82
6.3	Power of the laser beam versus incidence angle for 16, 18, and 20 pulses exposures	83
6.4	Refractive index versus number of pulses	85
6.5	The example of fringe pattern shifts by an amount of Δx (Pedrotti and Pedrotti, 1993)	86
6.6	Histogram of ablation depth upon fringes after 10, 12, and 14 pulses	90
6.7	Histogram of ablation depth upon fringes after 16, 18, and 20 pulses	91
6.8	Depthness as a function of number of pulses	92

LIST OF SYMBOLS

A	-	Area of high intensity distribution
$[A]$	-	Amplitude of wave
c	-	Speed of light in vacuum
d	-	Ablation depth
E	-	Pulse energy
$[E]_{\parallel}$	-	Light with electric vector
$[E_r]_{\parallel}$	-	Reflected light
$[E_t]_{\parallel}$	-	Transmitted light
F	-	Flatness
I	-	Intensity
L	-	Working distance
m	-	Integer
M	-	Order of interference
N	-	Number of pulses
n	-	Refractive index
P	-	Power
Δp	-	Optical path difference
t	-	Thickness
Δt	-	Changes thickness
V	-	Discharged voltage
W	-	Normal spacing (before exposure)
w	-	Fringes spacing after exposure
Δx	-	Shifted fringes
θ_i, θ_1	-	Incidence angle
θ_r, θ_2	-	Refraction angle
θ_p	-	Brewster's angle
ϕ	-	Optical phase
λ	-	Wavelength

LIST OF APPENDICES

APPENDIX	TITLE	PAGE
A	Specification of excimer laser	105
B	Specification of energy meter	106
C	Specification of BeamStar CCD Profiler	108

CHAPTER 1

INTRODUCTION

1.1 Overview

Micromachining technology is an exciting and emerging area of modern technology because it allows compact and minifeature sizes to be fabricated. It has been widely applied to various micro-systems, micro-sensors, micro-actuators, and micro-optics. Miniaturising devices using micro-optics revolutionise many electro-optical systems such as video cameras, video phones, compact disk data storage, robotics vision, optical scanners and high definition projection displays (Jay and Stern, 1994). Both higher accuracy and lower cost microlens array fabrication methods (Naessens *et al.*, 2003, and Pan and Shen, 2004) are needed to meet the rapid growth for these commercial devices.

The traditional mechanical approaches of cutting, drilling, and shaping materials are no longer satisfactory for fabricating micronscale structures. Instead, fabrication using beam techniques based on photons, electrons, and ions are used to produce high-resolution structures. Lasers have been proven as effective tools in micromachining. They have been used to solve fine machining problems in numerous fields such as medical devices, telecommunication, microelectronics, fibre optics, data storage, instrumentation, and micro optics. Although lasers battle with other technologies for micromachining applications, they are suitable for those application that demand more precision, speed, and “direct-write” capability. Lasers can also work on most materials and environmentally friendly (Chang and Molian, 1999).

Laser machining or laser ablation is a surface structuring technique based on the interaction of intense laser pulses with a material. It is extremely well suited for fabricating the microstructures on polymer surfaces. Laser machining has been proven to be a versatile technique for producing high accuracy dimension and repeatability of features in a wide diversity of materials. Due to the non-contact and direct-write nature of the process, the fabrication of the microstructure can take place in a very late stage of a heterogeneous assembly. This makes laser ablation very attractive for fabricating micro-optical components on opto-electronic assemblies in comparison to other fabrication technique like injection molding, embossing, and standard micro-electronic manufacturing process (Naessens *et al.*, 2000).

1.2 Laser Machining

High-power short-pulse laser ablation has been extensively applied in micro machining technology in recent years. Laser ablation (also known as laser machining) is most usually associated with the use of excimer lasers. Excimer laser ablation is a valuable micro-fabrication technology, which is particularly well-suited for surface structuring of polymers because of their excellent UV absorption and highly non-thermal ablation behaviour (Naessens *et al.*, 2003). It is now twenty three years since first appeared on using UV excimer lasers to ablate the material such as polymer (Dyer, 2003). Dyer has reviewed the basic mechanistic aspects of the UV laser-polymer interaction; photophysical and photochemical mechanisms. The interaction also accompanied by a visible plume, that is, the expanding cloud of volatile products that are expelled from the irradiated surface by each laser pulse.

Particularly, laser ablation was started by Srinivasan and Mayne-Banton (1982). They reported that the surface of polymer like PET (polyethylene terephthalate) could be ablated and etched by radiation of 193 nm (ArF excimer laser) wavelength without any subsequent processing. Since that time, the interaction of pulsed, ultraviolet laser radiation from an excimer laser (193 nm, 248 nm, 308 nm, or 351 nm) with organic polymer surface has been the subject of

intense research activity (Dyer, 1992). Until now, many research efforts are carried out to have a better understanding of excimer laser ablation of polymer.

Oldershaw (1993) has observed two features of excimer laser ablation. Firstly, the interaction between the UV radiation and polymer is much localised, so that patterns of high definition and controlled depth can be etched in the surface. Because of the strong absorption of many polymers at 193 nm ArF laser, the depth of etch for a single laser pulse is very small, usually less than 1 μm . Secondly, there is threshold laser fluence before it can ablate the surface. In discussing the UV-polymer interaction, Srinivasan (1993) has considered the power density of the radiation at the polymer surface instead of the fluence as it is commonly done.

In 1996, Dyer's group have done research on excimer laser ablation of low and high absorption index polymers. They have used High Speed Shadow Photography (HSSP), Probe Beam Deflection (PBD), and Time Resolved Interferometry (TRI) techniques to provide information about the ablation process. What has become clear from this activity is that laser parameter such as wavelength, pulse duration, and fluence, each of them has contributing effects to the ablation process and not all polymers exhibit the same ablation characteristics with a given set of irradiance conditions. A given polymer can exhibit a variety of ablation characteristics depending on the irradiance parameters applied (Dyer *et al.*, 1996).

Beside that, it is shown that the acoustic waves generated during laser ablation can be used to determine the ablation threshold and the ablation rate for different fluences and depths, and also to characterize the different regions of the process (Efthimiopoulus *et al.*, 1998). The ablation process was also analysed experimentally in terms of material removal rate, optical emission of the laser-induced plasma, hole geometry, debris production at the hole edge, and chemical changes in the polymer induced by the laser irradiation (Wesner *et al.*, 1999).

Optics for high power laser systems in fusion research requires very precise control of phase distribution for obtaining uniform irradiation intensity on the pellet

target. In the conventional optical fabrication, the control of the phase in the optics has been made by polishing the optics until the phase error is less than $\lambda/8$. This requirement causes very expensive prices of optical components for high power lasers. But then, Jitsuno (1999) has introduced a phase compensation technique, which is a cheap and rapid fabrication process of precise optical elements. This approach provides the way to control the phase of the optics, which is very important for many other applications in optics.

In order to fabricate micro channels, Wagner and Hoffman (1999) have performed multiple pulse laser ablation of stretched polymer with an ArF excimer laser (193 nm). The surface structure remaining after 'scanning ablation', is compared to the known results upon 'static ablation'. Yang and Pan (2003) used a numerical simulations technique to predict the profile of analogous microstructures following excimer laser ablation to obtain desired micro-optical components.

Naessens *et al.* (2003) have applied a fabrication technique for microlenses and arrays of microlenses using excimer laser ablation process. The process is based on scanning a polymer surface with a pulsed excimer beam along well-chosen multiple concentric contours and in this way microlenses of arbitrary shape can be realized. Once again, numerical simulation was used to predict the profile of a three-dimensional aspherical microlens and a microprism array (Pan and Shen, 2004). Based on the simulated results, the desired micro-optical lens profile was obtained using excimer laser ablated polymer. Recently, Jensen *et al.* (2005) has demonstrated a new method for forming microlenses or microlens arrays, which utilizes excimer laser degradation of PMMA followed by a thermal treatment.

From all research efforts, laser ablation and processing are applied in many area which covering fabrication of optical material, material removing, surface modification, surface cleaning and many more. It gives us an interest to study and characterize the fundamental of laser ablation. Although the application is wide, our interest study is lay on interaction of excimer laser with polymer material and our research in this field focusing towards the optical fabrication.

1.3 Interferometric Observation

Optical techniques are powerful for deformation analysis. Contour measurement by interferometry is used widely to determine the shape of a surface. Information about the surface of a static object can be obtained from interference fringes whose contour lines or fringes characterize the surface on which they are formed. There are two basic methods for measurement of surface shape or height profile by optical contouring: phase shifting and the Fourier transform.

In 1995, Jitsuno's group have made some basic fabrication experiments on the measurement of the ablation rate. They made on a different kinds of optical plastics and in situ interferometric observation of the surface figure of a PMMA plate. A new approach for mitigate some important disadvantages of optical plastics such as the bulk non-uniformity, the index drift due to the humidity absorption and the strong birefringence have been proposed using the plastic-glass hybrid component to reduce the thickness of plastic.

Scully *et al.* (1999) used a Fabry-Perot interferometer method to measure small changes in optical path length in the sample as a function of laser power, fluence, repetition rate and total accumulated energy of number of pulses. They were using 3 mm thick PMMA slab as a Fabry Perot etalon for measuring the optical path length changes at a selection of UV wavelength. When the UV irradiated was illuminated with a green He-Ne laser at 548 nm, shifts in reflected interference fringes were observed. These shifts indicate changes in sample thickness, refractive index, and penetration depth in agreement with other researchers.

The dynamic processes during laser ablation of polymers also have been studied by Hauer *et al.* (2003). They were using nanosecond-interferometry and shadowgraphy to compare the influence of the two absorption sites in the same and the two different polymers. Both methods have the potential to give strong indicating for the underlying mechanism.

Dennis *et al.* (2001) report on the technique for determining the change in the refractive index of photosensitive glass. They demonstrated interferometer-based technique on fibre perform and bulk glass samples, achieving an optical-path-difference (OPD) repeatability of 0.2 nm. But their technique was found to be insensitive to the effects of photodarkening and material compaction. Karaalioglu and Skarlatos (2003) have observed the surface profile of an aluminum (Al) thin film and its thickness by electronic speckle pattern interferometry. The Michelson interferometer was used as their basic interferometric system to obtain interference fringes on a CCD camera. These interference fringes depend on the path difference due to the surface contours of thin film. Then, they analyzed the interference fringes with the fast Fourier transform method.

Regarding to some of the papers reviewed, it encourages us to observe the result of fabrication process by using interferometry technique. Interferometer is a sensitive detector, which is suitable to observe any changes on the surface shape even though by a fundamental shot of excimer laser ablation.

1.4 Research Objective

This research was carried out in order to achieve the following objectives:-

1. to diagnose the ablation source
2. to determine the ablation threshold
3. to characterize the ablation effect by interferometry method
4. to estimate the ablation depth

1.5 Research Scopes

The ablation was conducted using UV light of ArF excimer laser. The laser was triggered externally in order to vary the number of pulses from 1 to 20 pulses. The optical material of polymethyl methacrylate (PMMA) was chosen as a

specimen. The multi exposure from single pulse was directed on the same spot. The ablation was verified based on the laser parameters including pumping voltage, working distance, and number of pulses. The ablation effect was measured and calculated using interferometry method. The quantifying involved, including shifted, intensity, and spacing of the fringes. Depthness of the sample at the ablated area was estimated by knowing its refractive index.

1.6 Thesis Outline

This thesis is divided into seven chapters. The first chapter is introducing the application of micromachining technology and its advantages upon traditional approaches. Some previous researches which are related to the laser machining or laser ablation and interferometric technique are reviewed. This chapter also emphasize the aim of this research.

Chapter 2 discuss the theories that are related to the research. These include mechanism of laser ablation, optical material and its affect on UV light, optical properties of the material that is refractive index, and also about the interference phenomenon.

Chapter 3 describes about methodology and equipments employed in this research such as excimer laser system, which include internal structures and external triggering. Measurement of pulse energy of excimer laser beam and its beam profiles were discussed. This chapter also describes about sample preparation and interferometer set up.

Characterization the source of ablation that is an excimer laser beam is found in Chapter 4. Firstly, it involved the pulse energy and peak power of the beam upon various laser parameters such as discharged voltage and number of pulses. Secondly, the beam profiles of the laser beam upon working distance and discharged voltage are described. Then, how to calculate the laser fluence are explained. This

is done in order to determine the appropriate laser energy or power needed during ablation works.

Chapter 5 explains about laser ablative figuring. The ablation effects occurred on the PMMA surface can be traced using interference method. The first disturbance detected was referred as ablation threshold. Then the deformation fringes were analyzed and quantified based on shifted, intensity, and spacing changes.

The estimation of ablation depth on PMMA sample is obtained in chapter 6. Prior to calculate the depth, the changes of refractive index of the exposed material was measured using Brewster angle. The depth was estimated based on refractive index, shifted fringes, and normal spacing.

Finally, chapter 7 conclude of the whole project. These provided with the problems involved during perform the project. Last but not least, some works to be carried out in the near future are suggested.

REFERENCES

- Boedeker Plastic, Inc. (2003). *Acrylic PMMA (Polymethyl-Methacrylate) Specifications*. Texas (USA): Datasheet.
- Chang, T. C. and Molian, P. A. (1999). Excimer Pulsed Laser Ablation of Polymers in Air and Liquids for Micromachining Applications. *Journal of Manufacturing Sys.* 1:1-17.
- Dennis, T., Gill, E. M., and Gilbert, S. L. (2001). Interferometric Measurement of Refractive Index Change in Photosensitive Glass. *Appl. Opt.* Vol. 40, No. 10 : 1663-1667.
- Diakouomos, C. D. and Raptis, I. (2003). In Situ Monitoring of Thermal Transitions in Thin Polymeric Films via Optical Interferometry. *Polymer.* 44:251-260.
- Dyer, P.E. (1992). Laser Ablation of Polymers. In: Boyd, I.W. ed. *Photochemical Processing of Electronic Materials*. London: Academic Press. 359.
- Dyer, P.E. (2003). Excimer Laser Polymer Ablation: Twenty Years On. *App. Phys. A. Mat. Sci. and Process.* 77:167-173.
- Dyer, P.E., Karnakis, D.M., Key, P.H., and Tait, J.P. (1996). Excimer Laser Ablation of Low and High Absorption Index Polymers. *Appl. Surface Science* 96-98:596-600.

- Efthimiopoulos, T., Kritsotakis, E., Kiagias, H., Savvakis, C., and Bertachas, Y. (1998). Laser Ablation Rate of Materials using the Generated Acoustic Waves. *J. Phys. D: Appl. Phys.* 31:2648-2652.
- Elias, H. G. (2003). *An Introduction to Plastics: Second, Completely Revised Edition*. Germany: Wiley-VCH.
- Francon, M. (1966). *Optical Interferometry*. New York: Academic Press Inc.
- GAMLaser Inc. (2003). *EX5 Excimer Laser Manual*. Florida: User Manual.
- Garbassi, F., Morra, M., and Occhiello, E. (1998). *Polymer Surface: From Physics to Technology*. Wiley: Chichester.
- Hariharan, P. (1985). *Optical Interferometry*. Australia: Academic Press.
- Hauer, M., Funk, D. J., Lippert, T., and Wokaun, A. (2003). Laser Ablation of Polymers Studied by ns-Interferometry and ns-Shadowgraphy Measurements. *Applied Surface Science* 208-209.
- Hetch, J. (1992). *Understanding Laser: An Entry-level Guide*. New York: IEEE Press.
- Hetch, E. and Zajac, A. (1989). *Optic*. New York: Addison Wesley Pub. Company.
- Hughes, M. (2002). Polarization by Reflection and Brewster Angle. *Laboratory Report*. United Kingdom: University of Durham.
- Jay, T. R. and Stern, M. B. (1994). Preshaping Photoresist for Refractive Microlens Fabrication. *Opt. Eng.* 33:3552-3555.

- Jensen, M. F., Kruhne, U., Christensen, L. H., and Geschke, O. (2005). Refractive Microlenses Produced by Excimer Laser Irradiation of Poly(methyl methacrylate). *J. Micromech. Microeng.* 15:91-97.
- Jitsuno, T (1999). Advance Optics, *Proc. Of Asian Science Seminar on High-Power Laser Matter Interactions*, 1:15Mo-I.
- Jitsuno, T., Tokumura, K., Nishi, N., Nakashima, N., and Nakai, S. (1995). UV Laser Ablative Figuring of Precise Optic. *Conf. of Laser & Elec. Optic (CLEO95)* Vol.1:132-133
- Karaalioglu, C. and Skarlatos, Y. (2003). Fourier Transform Method for Measurement of Thin Film Thickness by Speckle Interferometry. *Opt. Eng.* 42(6):1694-1698.
- Kobayashi, T. (1999). Laser Ablation. *Asian Science Seminar on High-Power Laser Matter Interactions*. Feb., 7-17, 1999. Osaka: 15Mo-IV, 1-21.
- Kopietz, M., Lechner, M.D., and Steinmeier, D.G. (1984). Light-Induced Refractive Index Changes in Polymethylmethacrylate (PMMA) blocks. *Polymer photochemistry* 5:109-119.
- Malacara, D. (1988). Interference. In: Malacara, D. ed. *Physical Optics and Light Measurement – Volume 26*. United State of America: Academic Press, Inc.
- Matrox Electronic System Ltd. *Matrox Inspector Version 2.1*. Canada: User Manual.
- Melles Griot Inc. (1997). *Optic Guide 5: Laser Acc. and Detectors*. USA: Catalogue.
- Mohd. Hazimin Mohd. Salleh (2003). *Development of Argon Flouride (ArF) Excimer Laser Ablation System and Its Diagnosis on Optical Materials*. Universiti Teknologi Malaysia: Degree of Master of Science (Physics).

- Naessens, K., Daele, P. V., and Baets, R. (2000). Microlens Fabrication in PMMA with Scanning Excimer Laser Ablation Techniques. *Proceedings Symposium IEEELEOS Benelux Chapter*, The Netherlands.
- Naessens, K., Ottevaere, H., Daele, P.V., and Baets, R. (2003). Flexible Fabrication of Microlenses in Polymer Layers with Excimer Laser Ablation. *Appl. Surf. Sci.* 9587:1-6.
- Noriah Bidin (2002). *Teknologi Laser*. Johor: Penerbit Universiti Teknologi Malaysia Skudai.
- Oldershaw, G.A. (1993). Excimer and CO₂ Laser Ablation of Organic Polymers. In: Kelly, J.M. and McArdle, C.B. ed. *Photochemistry and Polymeric System*.
- Ophir Optronics Ltd. (2003). *BeamStar CCD Laser Beam Profiler for Windows*. United State: User Manual.
- Pan, C. T. and Shen, S. C. (2004). Design and Fabrication of Polymeric Micro-optical Components using Excimer Laser Ablation. *Materials Science and Technology*, Feb. 2004; 20, 2; *ProQuest Science Journals*, pg. 270.
- Parker, S. P. (1988). *Optics Source Book*. United State of America: McGraw-Hill.
- Pedrotti, F. L. and Pedrotti, L. S. (1993). *Introduction to Optics*. 2nd Ed. New Jersey: Prentice-Hall Inc.
- Rabek, J. F. (1996). *Photodegradation of Polymer: Physical Characteristic and Applications*. Berlin: Producerserv Springer Produktion-Gesellschaft.
- Scully, P.J., Caulder, S. and Barlett, R. (1999). UV Laser Photo-induced Refractive Index Changes in Polymethyl Methacrylate and Plastic Optical Fibres for Application as Sensor and Devices. *Cen. Laser Ann. Report* 1:145-147.

- Sirohi, R. S. (1985). *A Course of Experiments with He-Ne Laser*. New Delhi: Wiley Eastern Ltd.
- Sony Tektronix. *AFG 310 and AFG 320 Arbitrary Function Generator 071-0175-07*. Japan: User Manual.
- Srinivasan, R. (1993). Interactions of Polymer Surfaces with Ultraviolet Laser Pulses. In: Kelly, J.M. and McArdle, C.B. ed. *Photochemical and Polymeric System*.
- Srinivasan, R., Mayne-Banton, V., (1982). Self-developing Photoetching of Poly(ethylene terephthalate) Film by Far Ultraviolet Excimer Laser Radiation. *Appl. Phys. Lett.* 41(6):576-578.
- Wagner, F. and Hoffman, P. (1999). Structure Formation in Excimer Laser Ablation of Stretched Poly(ethylene terephthalate) (PET): The Influence of Scanning Ablation. *Appl. Phys. A* 69:S841-S844.
- Wang, J., Niino, H., and Yabe, A. (2001). Etching of Transparent Materials by Laser Ablation of an Organic Solution. *RIKEN Review* (32).
- Wesner, D.A., Aden, M., Gottman, J., Husmann, A., and Kreutz, E.W. (1999). Material Removal and Chemical and Structural Changes Induced by Irradiation of Polymer Surfaces with KrF Excimer Laser Radiation. *Fresenius J. Anal. Chem.* 365:183-187.
- Yang, H., and Pan, C.T. (2003). Analogous Micro-optical Components Fabricated Using Excimer Laser Ablation. *Tamkang Journal of Science and Engineering*, Vol. 6, No. 3, pp. 145-150.